

# NLA44599

## Low Voltage Single Supply Dual DPDT Analog Switch

The NLA44599 is an advanced CMOS dual-independent DPDT (double pole-double throw) analog switch, fabricated with silicon gate CMOS technology. It achieves high-speed propagation delays and low ON resistances while maintaining CMOS low-power dissipation. This DPDT controls analog and digital voltages that may vary across the full power-supply range (from  $V_{CC}$  to GND).

The device has been designed so the ON resistance ( $R_{ON}$ ) is much lower and more linear over input voltage than  $R_{ON}$  of typical CMOS analog switches.

The channel-select input structure provides protection when voltages between 0 V and 5.5 V are applied, regardless of the supply voltage. This input structure helps prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

The NLA44599 can also be used as a quad 2-to-1 multiplexer-demultiplexer analog switch with two Select pins that each controls two multiplexer-demultiplexers.

- Select Pins Compatible with TTL Levels
- Channel Select Input Over-Voltage Tolerant to 5.5 V
- Fast Switching and Propagation Speeds
- Break-Before-Make Circuitry
- Low Power Dissipation:  $I_{CC} = 2 \mu A$  (Max) at  $T_A = 25^\circ C$
- Diode Protection Provided on Channel Select Input
- Improved Linearity and Lower ON Resistance over Input Voltage
- Latch-up Performance Exceeds 300 mA
- ESD Performance: HBM > 2000 V; MM > 200 V
- Chip Complexity: 158 FETs



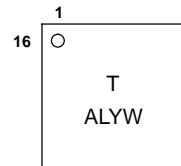
**ON Semiconductor®**

<http://onsemi.com>

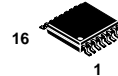
### MARKING DIAGRAMS



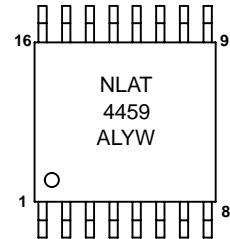
**QFN-16**  
**MN SUFFIX**  
**CASE 485G**



(TOP VIEW)



**TSSOP-16**  
**DT SUFFIX**  
**CASE 948F**

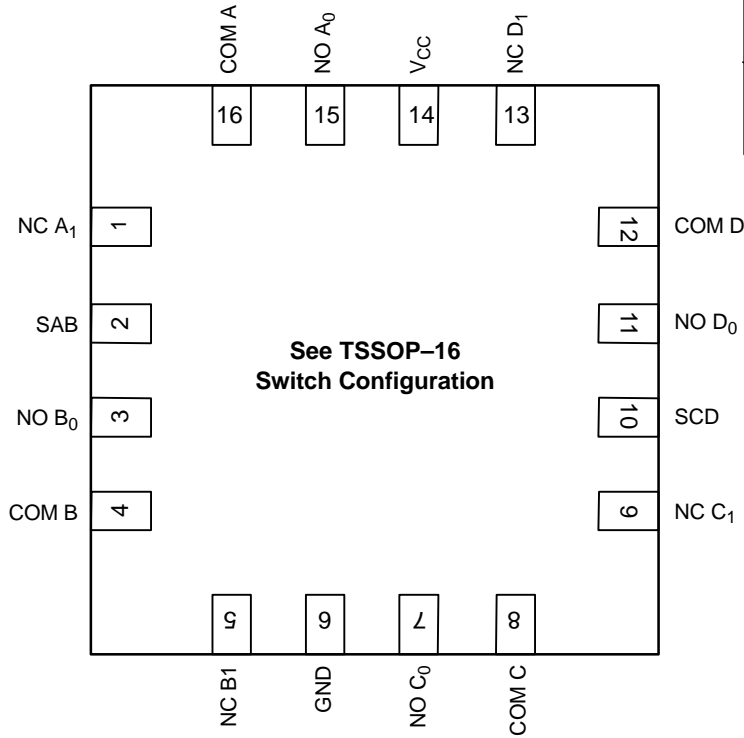


A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

QFN-16 PACKAGE



FUNCTION TABLE

Select XY	ON Channel	Select AB or CD	ON Channel
L	NC to COM	L	NC to COM
H	NO to COM	H	NO to COM

TSSOP-16 PACKAGE

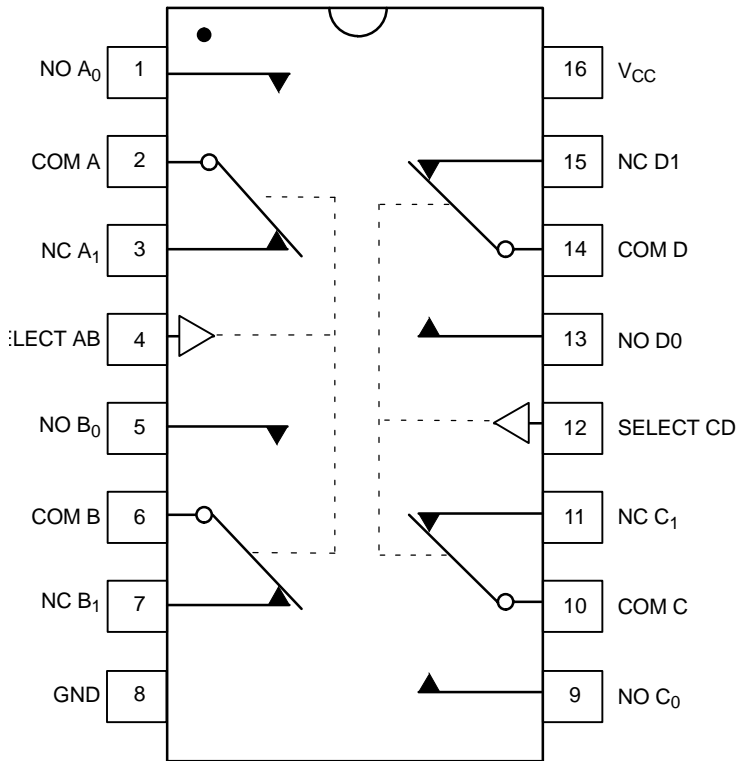


Figure 1. Logic Diagram

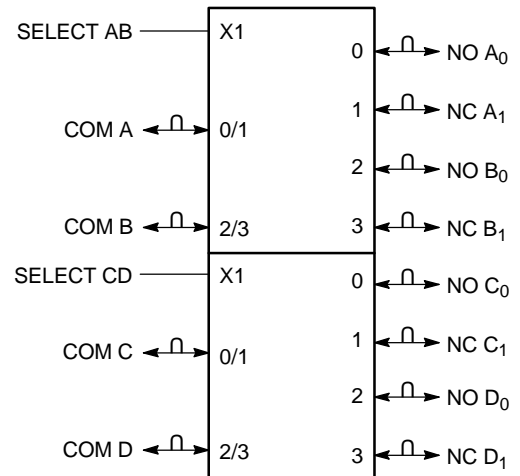


Figure 2. IEC Logic Symbol

# MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Positive DC Supply Voltage	− 0.5 to + 7.0	V
V <sub>IS</sub>	Analog Input Voltage (V <sub>NO</sub> or V <sub>COM</sub> )	− 0.5 ≤ V <sub>IS</sub> ≤ V <sub>CC</sub> + 0.5	V
V <sub>IN</sub>	Digital Select Input Voltage	− 0.5 ≤ V <sub>I</sub> ≤ + 7.0	V
I <sub>IK</sub>	DC Current, Into or Out of Any Pin	± 50	mA
P <sub>D</sub>	Power Dissipation in Still Air	TSSOP−16 450	mW
T <sub>STG</sub>	Storage Temperature Range	− 65 to + 150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T <sub>J</sub>	Junction Temperature Under Bias	150	°C
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 30% – 35% UL−94−VO (0.125 in)	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3) 2000 200 1000	V
I <sub>LATCH-UP</sub>	Latch-Up Performance	Above V <sub>CC</sub> and Below GND at 125°C (Note 4) ± 300	mA
θ <sub>JA</sub>	Thermal Resistance	TSSOP−16 164	°C/W

Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Extended exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

1. Tested to EIA/JESD22−A114−A.
2. Tested to EIA/JESD22−A115−A.
3. Tested to JESD22−C101−A.
4. Tested to EIA/JESD78.

# RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage	2.0	5.5	V
V <sub>IN</sub>	Digital Select Input Voltage	GND	5.5	V
V <sub>IS</sub>	Analog Input Voltage (NC, NO, COM)	GND	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature Range	− 55	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise or Fall Time, SELECT	V <sub>CC</sub> = 3.3 V ± 0.3 V V <sub>CC</sub> = 5.0 V ± 0.5 V 0 0	100 20	ns/V

# DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

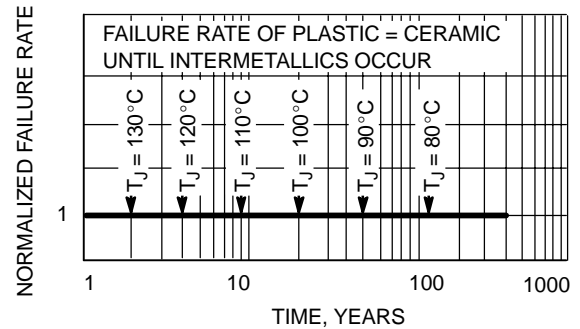


Figure 3. Failure Rate vs. Time Junction Temperature

**DC CHARACTERISTICS – Digital Section** (Voltages Referenced to GND)

Symbol	Parameter	Condition	V <sub>CC</sub>	Guaranteed Limit			Unit
				– 55°C to 25°C	< 85°C	< 125°C	
V <sub>IH</sub>	Minimum High–Level Input Voltage, Select Inputs		3.0	2.0	2.0	2.0	V
			4.5	2.0	2.0	2.0	
			5.5	2.0	2.0	2.0	
V <sub>IL</sub>	Maximum Low–Level Input Voltage, Select Inputs		3.0	0.5	0.5	0.5	V
			4.5	0.8	0.8	0.8	
			5.5	0.8	0.8	0.8	
I <sub>IN</sub>	Maximum Input Leakage Current, Select Inputs	V <sub>IN</sub> = 5.5 V or GND	5.5	± 0.2	± 2.0	± 2.0	μA
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> = 5.5 V or GND	0	± 10	± 10	± 10	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current	Select and V <sub>IS</sub> = V <sub>CC</sub> or GND	5.5	4.0	4.0	8.0	μA

**DC ELECTRICAL CHARACTERISTICS – Analog Section**

Symbol	Parameter	Condition	V <sub>CC</sub>	Guaranteed Limit			Unit
				– 55°C to 25°C	< 85°C	< 125°C	
R <sub>ON</sub>	Maximum “ON” Resistance (Figures 17 – 23)	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> V <sub>IS</sub> = GND to V <sub>CC</sub>  I <sub>IN</sub>   ≤ 10.0 mA	2.5	85	95	105	Ω
			3.0	45	50	55	
			4.5	30	35	40	
			5.5	25	30	35	
R <sub>FLAT</sub> (ON)	ON Resistance Flatness (Figures 17 – 23)	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub>  I <sub>IN</sub>   ≤ 10.0 mA V <sub>IS</sub> = 1 V, 2 V, 3.5 V	4.5	4	4	5	Ω
I <sub>NC(OFF)</sub> I <sub>NO(OFF)</sub>	NO or NC Off Leakage Current (Figure 9)	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> V <sub>NO</sub> or V <sub>NC</sub> = 1.0 V <sub>COM</sub> 4.5 V	5.5	1	10	100	nA
I <sub>COM(ON)</sub>	COM ON Leakage Current (Figure 9)	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> V <sub>NO</sub> 1.0 V or 4.5 V with V <sub>NC</sub> floating or V <sub>NO</sub> 1.0 V or 4.5 V with V <sub>NO</sub> floating V <sub>COM</sub> = 1.0 V or 4.5 V	5.5	1	10	100	nA

**AC ELECTRICAL CHARACTERISTICS** (Input  $t_r = t_f = 3.0$  ns)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> (V)	V <sub>IS</sub> (V)	Guaranteed Maximum Limit							Unit
					− 55° C to 25° C			< 85° C		< 125° C		
					Min	Typ*	Max	Min	Max	Min	Max	
t <sub>ON</sub>	Turn-On Time (Figures 12 and 13)	R <sub>L</sub> = 300 Ω, C <sub>L</sub> = 35 pF (Figures 5 and 6)	2.5	2.0	5	23	35	5	38	5	41	ns
			3.0	2.0	5	16	24	5	27	5	30	
			4.5	3.0	2	11	16	2	19	2	22	
			5.5	3.0	2	9	14	2	17	2	20	
t <sub>OFF</sub>	Turn-Off Time (Figures 12 and 13)	R <sub>L</sub> = 300 Ω, C <sub>L</sub> = 35 pF (Figures 5 and 6)	2.5	2.0	1	7	12	1	15	1	18	ns
			3.0	2.0	1	5	10	1	13	1	16	
			4.5	3.0	1	4	6	1	9	1	12	
			5.5	3.0	1	3	5	1	8	1	11	
t <sub>BBM</sub>	Minimum Break-Before-Make Time	V <sub>IS</sub> = 3.0 V (Figure 4) R <sub>L</sub> = 300 Ω, C <sub>L</sub> = 35 pF	2.5	2.0	1	12		1		1		ns
			3.0	2.0	1	11		1		1		
			4.5	3.0	1	6		1		1		
			5.5	3.0	1	5		1		1		

\*Typical Characteristics are at 25°C.

		Typical @ 25, VCC = 5.0 V	pF
C <sub>IN</sub>	Maximum Input Capacitance, Select Input	8	
C <sub>NO</sub> or C <sub>NC</sub>	Analog I/O (Switch Off)	10	
C <sub>COM</sub>	Common I/O (Switch Off)	10	
C <sub>(ON)</sub>	Feedthrough (Switch On)	20	

**ADDITIONAL APPLICATION CHARACTERISTICS** (Voltages Referenced to GND Unless Noted)

Symbol	Parameter	Condition	V <sub>CC</sub> V	Typical	Unit
				25° C	
BW	Maximum On-Channel – 3 dB Bandwidth or Minimum Frequency Response (Figure 11)	V <sub>IN</sub> = 0 dBm V <sub>IN</sub> centered between V <sub>CC</sub> and GND (Figure 7)	3.0	145	MHz
			4.5	170	
			5.5	175	
V <sub>ONL</sub>	Maximum Feedthrough On Loss	V <sub>IN</sub> = 0 dBm @ 100 kHz to 50 MHz V <sub>IN</sub> centered between V <sub>CC</sub> and GND (Figure 7)	3.0	–3	dB
			4.5	–3	
			5.5	–3	
V <sub>ISO</sub>	Off-Channel Isolation (Figure 10)	f = 100 kHz; V <sub>IS</sub> = 1 V RMS V <sub>IN</sub> centered between V <sub>CC</sub> and GND (Figure 7)	3.0	–93	dB
			4.5	–93	
			5.5	–93	
Q	Charge Injection Select Input to Common I/O (Figure 15)	V <sub>IN</sub> = V <sub>CC</sub> to GND, F <sub>IS</sub> = 20 kHz t <sub>r</sub> = t <sub>f</sub> = 3 ns R <sub>IS</sub> = 0 Ω, C <sub>L</sub> = 1000 pF Q = C <sub>L</sub> * ΔV <sub>OUT</sub> (Figure 8)	3.0	1.5	pC
			5.5	3.0	
THD	Total Harmonic Distortion THD + Noise (Figure 14)	F <sub>IS</sub> = 20 Hz to 100 kHz, R <sub>L</sub> = R <sub>gen</sub> = 600 Ω, C <sub>L</sub> = 50 pF V <sub>IS</sub> = 5.0 V <sub>PP</sub> sine wave	5.5	0.1	%
VCT	Channel to Channel Crosstalk	f = 100 kHz; V <sub>IS</sub> = 1 V RMS V <sub>IN</sub> centered between V <sub>CC</sub> and GND (Figure 7)	5.5	–90	dB
			3.0	–90	

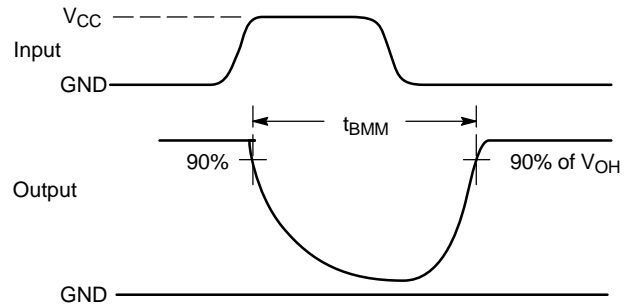
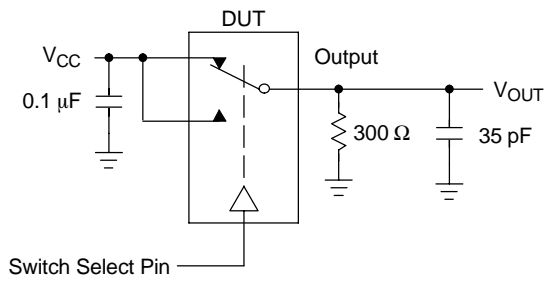


Figure 4.  $t_{BMM}$  (Time Break-Before-Make)

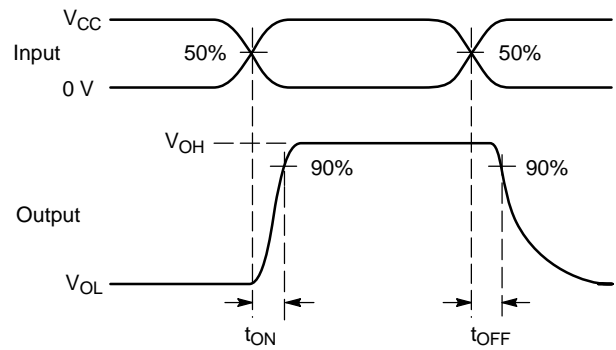
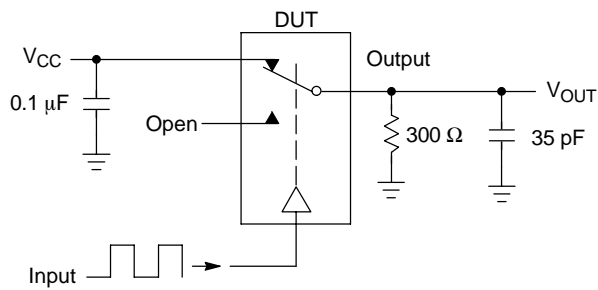


Figure 5.  $t_{ON}/t_{OFF}$

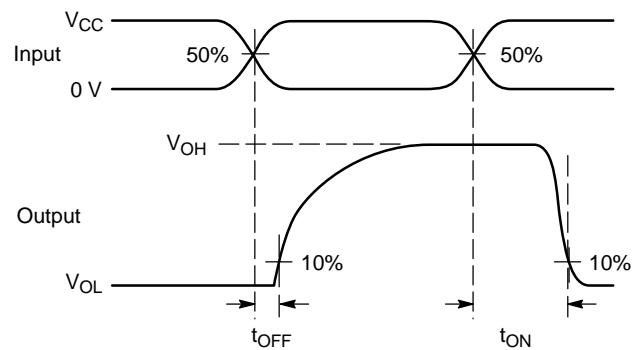
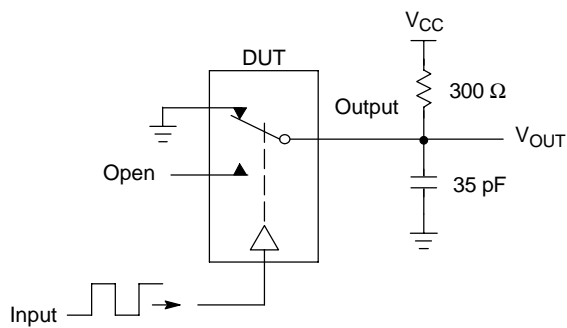
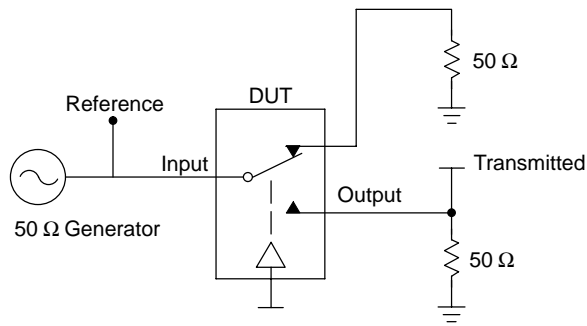


Figure 6.  $t_{ON}/t_{OFF}$



Channel switch control/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch.  $V_{ISO}$ , Bandwidth and  $V_{ONL}$  are independent of the input signal direction.

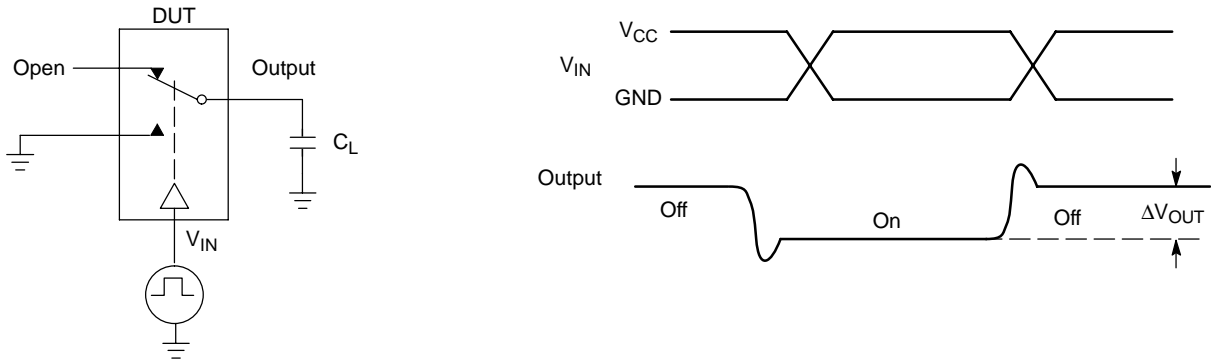
$$V_{ISO} = \text{Off Channel Isolation} = 20 \text{ Log} \left( \frac{V_{OUT}}{V_{IN}} \right) \text{ for } V_{IN} \text{ at } 100 \text{ kHz}$$

$$V_{ONL} = \text{On Channel Loss} = 20 \text{ Log} \left( \frac{V_{OUT}}{V_{IN}} \right) \text{ for } V_{IN} \text{ at } 100 \text{ kHz to } 50 \text{ MHz}$$

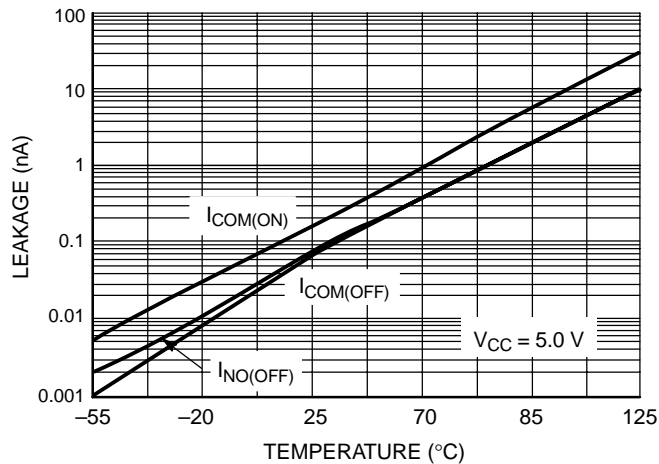
Bandwidth (BW) = the frequency 3 dB below  $V_{ONL}$

$V_{CT}$  = Use  $V_{ISO}$  setup and test to all other switch analog input/outputs terminated with 50 Ω

**Figure 7. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/ $V_{ONL}$**



**Figure 8. Charge Injection: (Q)**



**Figure 9. Switch Leakage vs. Temperature**

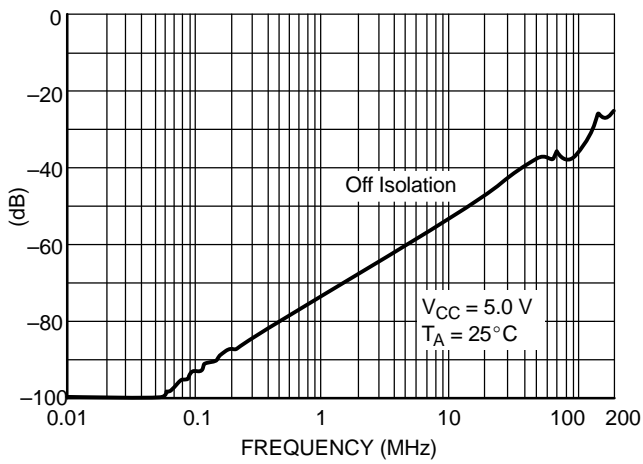


Figure 10. Off-Channel Isolation

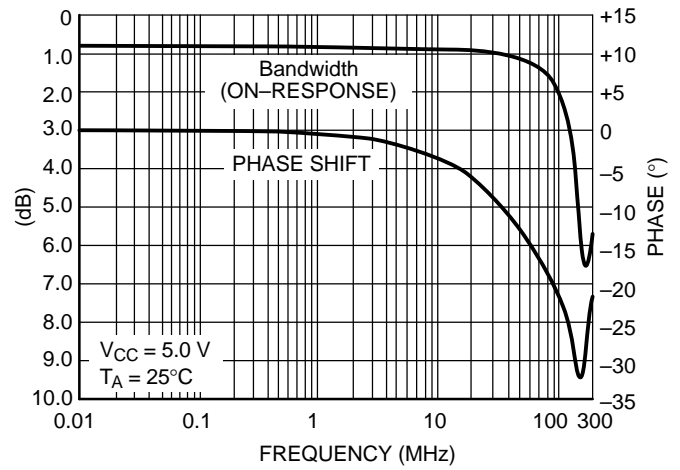


Figure 11. Typical Bandwidth and Phase Shift

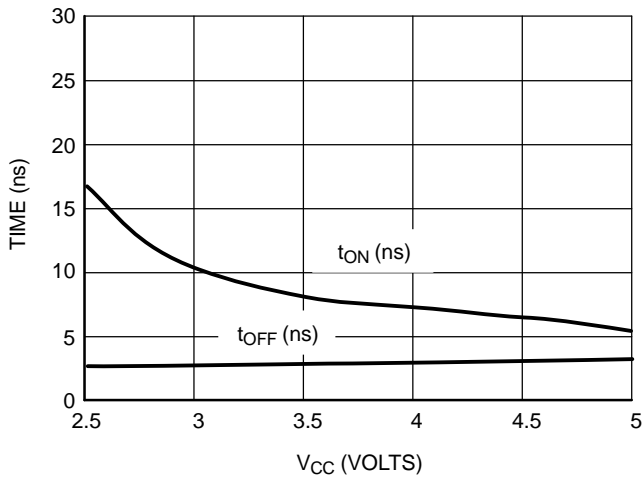


Figure 12.  $t_{ON}$  and  $t_{OFF}$  vs.  $V_{CC}$  at  $25^\circ\text{C}$

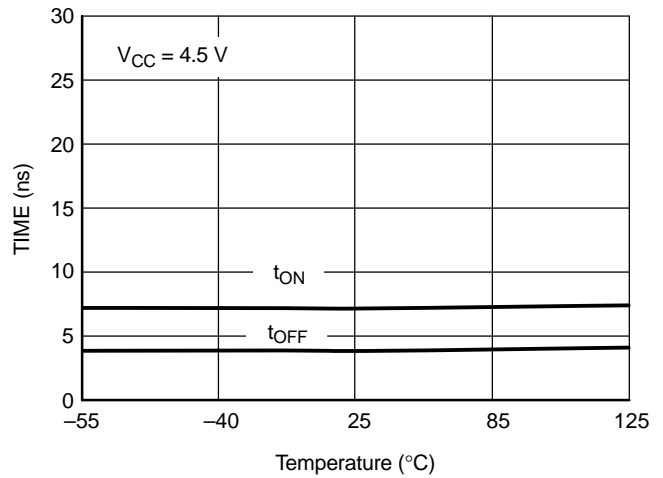


Figure 13.  $t_{ON}$  and  $t_{OFF}$  vs. Temp

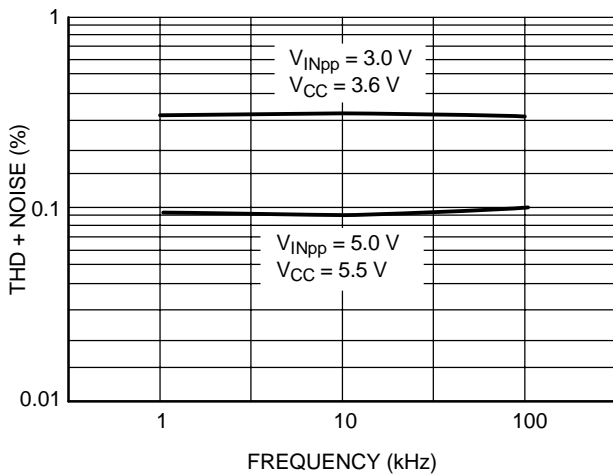


Figure 14. Total Harmonic Distortion Plus Noise vs. Frequency

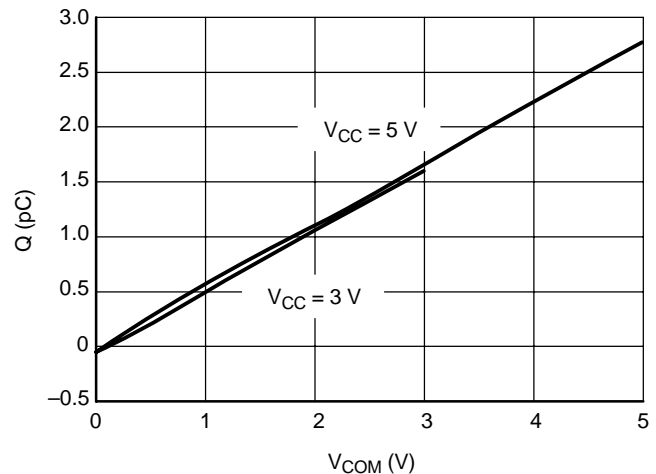


Figure 15. Charge Injection vs. COM Voltage



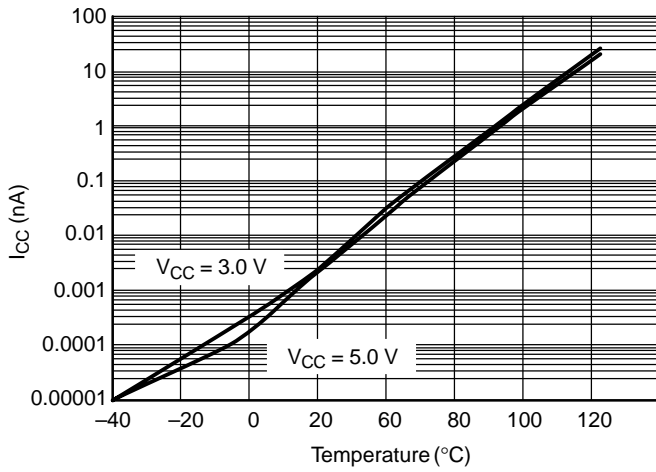


Figure 16.  $I_{CC}$  vs. Temp,  $V_{CC} = 3\text{ V}$  and  $5\text{ V}$

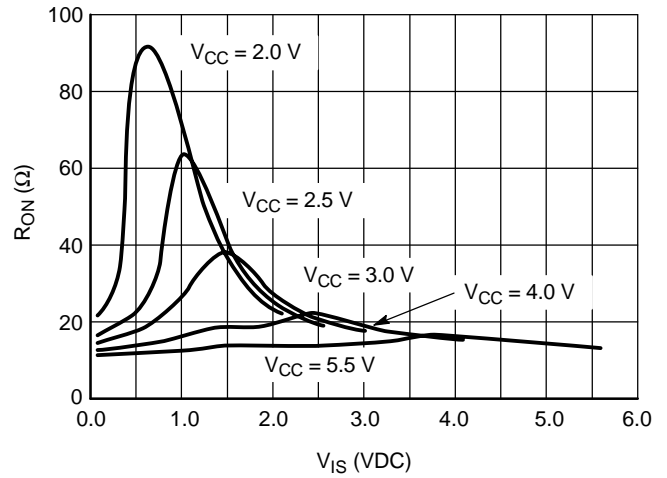


Figure 17.  $R_{ON}$  vs.  $V_{CC}$ , Temp =  $25^{\circ}\text{C}$

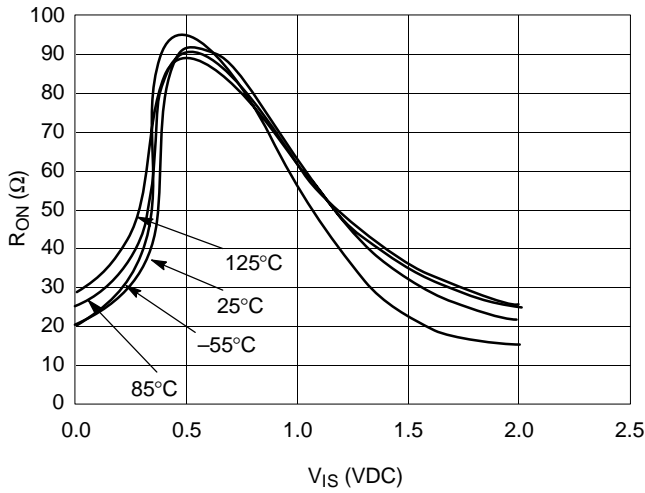


Figure 18.  $R_{ON}$  vs Temp,  $V_{CC} = 2.0\text{ V}$

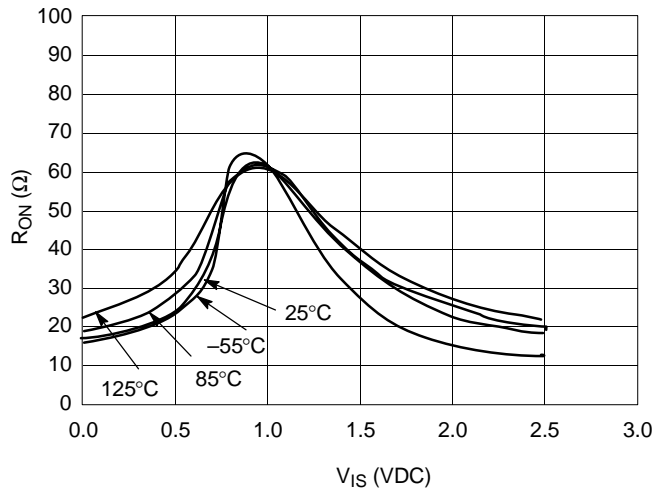


Figure 19.  $R_{ON}$  vs. Temp,  $V_{CC} = 2.5\text{ V}$

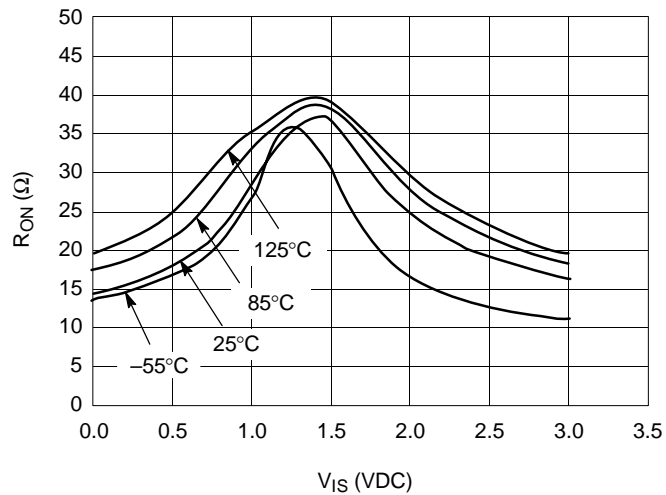


Figure 20.  $R_{ON}$  vs. Temp,  $V_{CC} = 3.0\text{ V}$

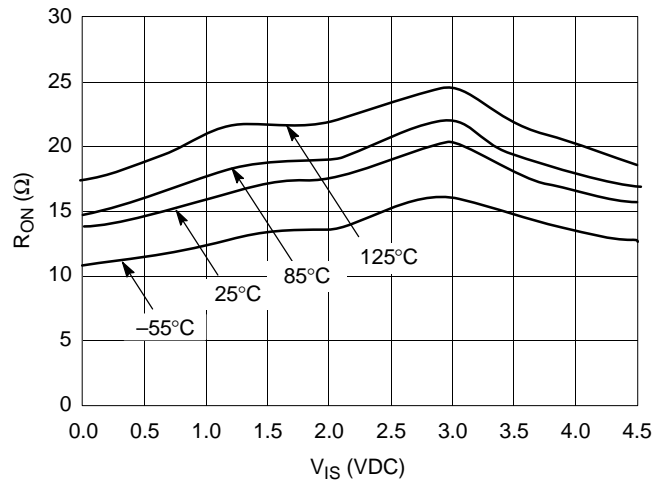


Figure 21.  $R_{ON}$  vs. Temp,  $V_{CC} = 4.5\text{ V}$

# NLAST44599

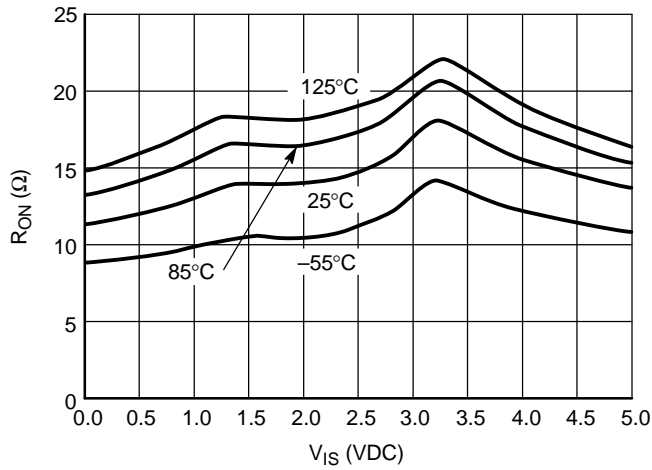


Figure 22.  $R_{ON}$  vs. Temp,  $V_{CC} = 5.0$  V

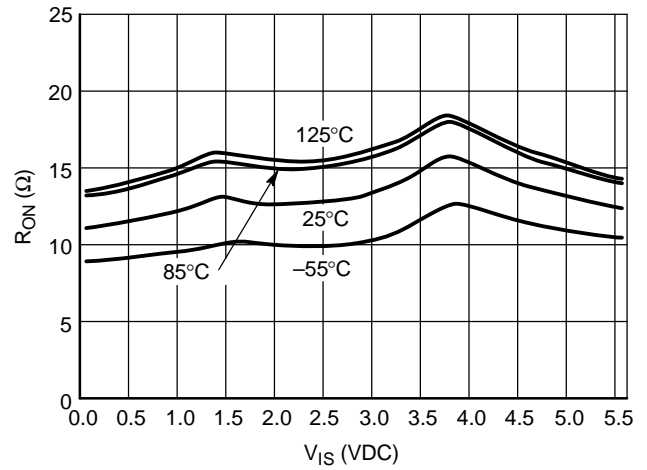


Figure 23.  $R_{ON}$  vs. Temp,  $V_{CC} = 5.5$  V

## DEVICE ORDERING INFORMATION

Device Order Number	Device Nomenclature					Package Type	Tape and Reel Size
	Circuit Indicator	Technology	Device Function	Package Suffix	Tape and Reel Suffix		
NLAST44599MNR2	NL	AS	44599	MN	R2	QFN	7-inch/2500 Unit
NLAST44599DTR2	NL	AS	44599	DT	R2	TSSOP	13-inch/2500 Unit
NLAST44599MN	NL	AS	44599	MN		QFN	124 Unit Rail
NLAST44599DT	NL	AS	44599	DT		TSSOP	96 Unit Rail

## PIN1/PRODUCT ORIENTATION CARRIER TAPE

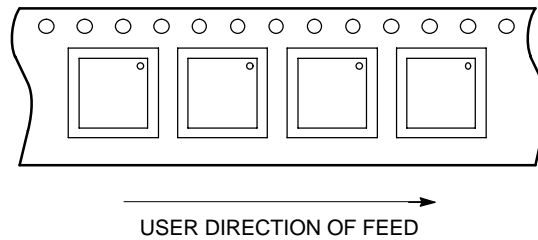
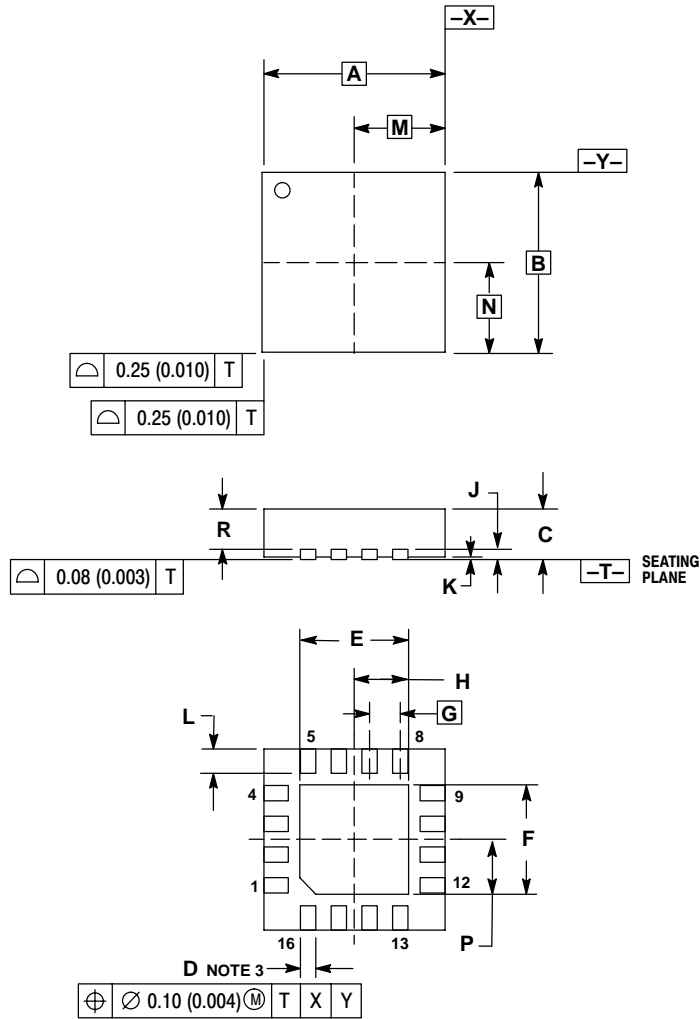


Figure 24.

# NLAST44599

## PACKAGE DIMENSIONS

QFN-16  
MN SUFFIX  
CASE 485G-01  
ISSUE O



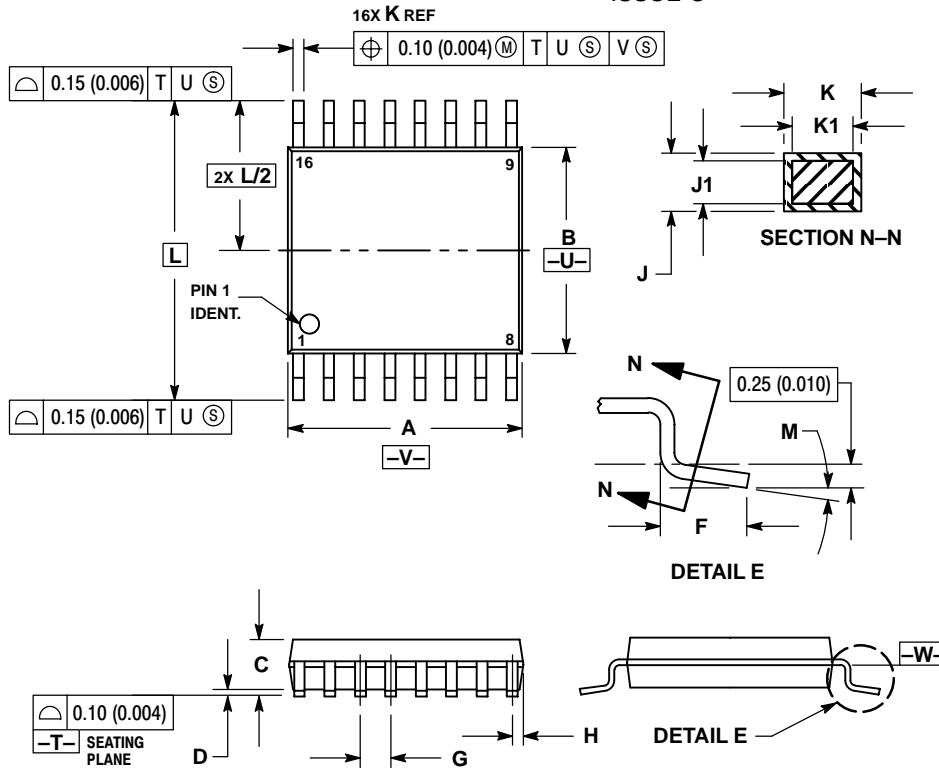
### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION D APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	3.00 BSC		0.118 BSC	
B	3.00 BSC		0.118 BSC	
C	0.80	1.00	0.031	0.039
D	0.23	0.28	0.009	0.011
E	1.75	1.85	0.069	0.073
F	1.75	1.85	0.069	0.073
G	0.50 BSC		0.020 BSC	
H	0.875	0.925	0.034	0.036
J	0.20 REF		0.008 REF	
K	0.00	0.05	0.000	0.002
L	0.35	0.45	0.014	0.018
M	1.50 BSC		0.059 BSC	
N	1.50 BSC		0.059 BSC	
P	0.875	0.925	0.034	0.036
R	0.60	0.80	0.024	0.031

## PACKAGE DIMENSIONS


TSSOP-16  
DT SUFFIX  
CASE 948F-01  
ISSUE O



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC	0.026 BSC		
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC	0.252 BSC		
M	0°	8°	0°	8°

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